



PK158 (v1.3) July 27, 2012

100% Material Declaration Data Sheet FT256**Average Weight: 0.7530g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.020003	2.656
	Silicon	7440-21-3	100.00		0.020003	
Die Attach					0.006372	0.846
	Silver (Ag)	7440-22-4	77.50		0.004938	
	Bismaleimide monomer	Trade Secret	15.00		0.000956	
	Acrylate monomer	Trade Secret	7.50		0.000478	
Mold Compound					0.382614	50.813
	Epoxy Resin A	Trade Secret	3.00		0.011478	
	Epoxy Resin B	Trade Secret	3.00		0.011478	
	Phenol Resin A	Trade Secret	3.00		0.011478	
	Phenol Resin B	Trade Secret	3.00		0.011478	
	Metal Hydroxide	Trade Secret	1.50		0.005739	
	Carbon Black	1333-86-4	0.30		0.001148	
	Silica Fused	60676-86-0	70.90		0.271273	
	Silica Fused	7631-86-9	15.00		0.057392	
	Silica, crystalline	14808-60-7	0.30		0.001148	
Gold Wire					0.009626	1.278
	Gold (Au)	7440-57-5	99.05		0.009534	
	Palladium	7440-05-3	0.95		0.000091	
Solder Ball					0.140993	18.725
	Tin (Sn)	7440-31-5	63.00		0.088826	
	Lead (Pb)	7439-92-1	37.00		0.052167	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Substrate					0.193378	25.681
	Copper (Cu)	7440-50-8	17.68		0.034198	
	Nickel (Ni)	7440-02-0	4.23		0.008174	
	Gold (Ag)	7440-57-5	0.50		0.000976	
	Glass Fiber	65997-17-3	16.27		0.031453	
	Non Halogen Fire Retardant	1675-54-3	0.01		0.000019	
	Bt Core	105391-33-1, 25722-66-1, 9003-36-5, 21645-51-2, 7440-38-2	46.23		0.089404	
	Solder Mask	13676-54-5, 25722-66-1, 147-14-8, 7727-43-7, 61790-53-2, 14807-96-6, 461-58-5, 7723-14-0	15.08		0.029152	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/21/06	1.0	Initial Xilinx release.
06/19/06	1.1	100% Material Declaration
09/21/06	1.2	Updated Component Description
07/27/12	1.3	Updated Component Descriptions and Weights

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